

# LOW SKEW, 1-TO-8 CRYSTAL-TO-LVCMOS FANOUT BUFFER

ICS839081-02

## GENERAL DESCRIPTION



The ICS839081-02 is a low skew, high performance 1-to-8 Crystal Oscillator/3.3V LVCMOS-to-3.3V LVCMOS fanout buffer and a member of the HiPerClock<sup>SM</sup> family of High Performance Clock Solutions from IDT. The ICS839081-02 has selectable single ended clock or two crystal-oscillator inputs. There is an output enable to disable the outputs by placing them into a high-impedance state.

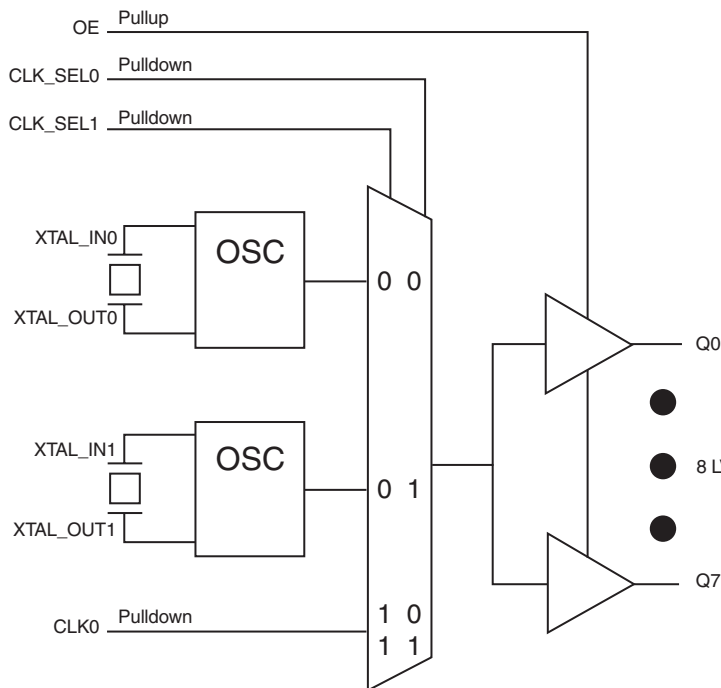
Guaranteed output and part-to-part skew characteristics make the ICS839081-02 ideal for those applications demanding well defined performance and repeatability.

## FEATURES

- Eight LVCMOS/LVTTL outputs (19Ω typical output impedance)
- Two Crystal oscillator input pairs One LVCMOS/LVTTL clock input
- Crystal input frequency range: 10MHz - 40MHz
- Output frequency: 200MHz (typical) CLK0
- Output Skew: TBD
- Part to Part Skew: TBD
- RMS phase jitter @ 25MHz (100Hz - 1MHz): 0.22ps (typical)  $V_{DD} = V_{DDO} = 3.3V$ 

Offset	Noise Power
100Hz .....	-111.4 dBc/Hz
1kHz .....	-139.9 dBc/Hz
10kHz .....	-157.3 dBc/Hz
100kHz .....	-157.5 dBc/Hz
- Supply Voltage Modes: (Core/Output)
  - 3.3V/3.3V
  - 3.3V/2.5V
  - 3.3V/1.8V
  - 2.5V/2.5V
  - 2.5V/1.8V
- -40°C to 85°C ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

## BLOCK DIAGRAM



## PIN ASSIGNMENT

V <sub>DD</sub>	1	24	GND
XTAL_IN0	2	23	XTAL_IN1
XTAL_OUT0	3	22	XTAL_OUT1
V <sub>DDO</sub>	4	21	V <sub>DDO</sub>
Q0	5	20	Q7
Q1	6	19	Q6
GND	7	18	GND
Q2	8	17	Q5
Q3	9	16	Q4
V <sub>DDO</sub>	10	15	V <sub>DDO</sub>
CLK_SEL0	11	14	CLK_SEL1
CLK0	12	13	OE

**ICS839081-02**  
**24-Lead, 173-MIL TSSOP**  
 4.4mm x 7.8mm x 0.92mm  
 body package  
**G Package**  
 Top View

The Preliminary Information presented herein represents a product in pre-production. The noted characteristics are based on initial product characterization and/or qualification. Integrated Device Technology, Incorporated (IDT) reserves the right to change any circuitry or specifications without notice.

TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1	V <sub>DD</sub>	Power		Core supply pin.
2, 3	XTAL_IN0, XTAL_OUT0	Input		Crystal oscillator interface. XTAL_IN0 is the input. XTAL_OUT0 is the output.
4, 10, 15, 21	V <sub>DDO</sub>	Power		Output supply pins.
5, 6, 8, 9, 16, 17, 19, 20	Q0, Q1, Q2, Q3, Q4, Q5, Q6, Q7	Output		Single-ended clock outputs. LVCMOS/LVTTL interface levels.
7, 18, 24	GND	Power		Power supply ground.
11, 14	CLK_SEL0, CLK_SEL1	Input	Pulldown	Clock select inputs. See Table 3, Input Reference Function Table. LVCMOS / LVTTL interface levels.
12	CLK0	Input	Pulldown	Single-ended clock input. LVCMOS/LVTTL interface levels.
13	OE	Input	Pullup	Output enable. When LOW, outputs are in HIGH impedance state. When HIGH, outputs are active. LVCMOS / LVTTL interface levels.
22, 23	XTAL_OUT1, XTAL_IN1	Input		Crystal oscillator interface. XTAL_IN1 is the input. XTAL_OUT1 is the output.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ
C <sub>PD</sub>	Power Dissipation Capacitance (per output)	V <sub>DDO</sub> = 3.465V		7		pF
		V <sub>DDO</sub> = 2.625V		7		pF
		V <sub>DDO</sub> = 2V		6		pF
R <sub>OUT</sub>	Output Impedance	V <sub>DDO</sub> = 3.3V ± 5%		19		Ω
		V <sub>DDO</sub> = 2.5V ± 5%		21		Ω
		V <sub>DDO</sub> = 1.8V ± 0.2V		32		Ω

TABLE 3. INPUT REFERENCE FUNCTION TABLE

Control Inputs		Reference
CLK_SEL1	CLK_SEL0	
0	0	XTAL0 (default)
0	1	XTAL1
1	0	CLK0
1	1	CLK0

## ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $V_{DD}$	4.6V
Inputs, $V_I$	-0.5V to $V_{DD} + 0.5V$
Outputs, $V_O$	-0.5V to $V_{DDO} + 0.5V$
Package Thermal Impedance, $\theta_{JA}$	84.6°C/W (0 mps)
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 4A. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Core Supply Voltage		3.135	3.3	3.465	V
$V_{DDO}$	Output Supply Voltage		3.135	3.3	3.465	V
$I_{DD}$	Power Supply Current	No Load & XTALx selected		25		mA
		No Load & CLK0 selected		0		mA
$I_{DDO}$	Output Supply Current	No Load & CLK0 selected		0		mA

TABLE 4B. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 2.5V \pm 5\%$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Core Supply Voltage		3.135	3.3	3.465	V
$V_{DDO}$	Output Supply Voltage		2.375	2.5	2.625	V
$I_{DD}$	Power Supply Current	No Load & XTALx selected		25		mA
		No Load & CLK0 selected		0		mA
$I_{DDO}$	Output Supply Current	No Load & CLK0 selected		0		mA

TABLE 4C. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Core Supply Voltage		3.135	3.3	3.465	V
$V_{DDO}$	Output Supply Voltage		1.6	1.8	2.0	V
$I_{DD}$	Power Supply Current	No Load & XTALx selected		25		mA
		No Load & CLK0 selected		0		mA
$I_{DDO}$	Output Supply Current	No Load & CLK0 selected		0		mA

TABLE 4D. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = V_{DDO} = 2.5V \pm 5\%$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Core Supply Voltage		2.375	2.5	2.625	V
$V_{DDO}$	Output Supply Voltage		2.375	2.5	2.625	V
$I_{DD}$	Power Supply Current	No Load & XTALx selected		15		mA
		No Load & CLK0 selected		0		mA
$I_{DDO}$	Output Supply Current	No Load & CLK0 selected		0		mA

TABLE 4E. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = 2.5V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Core Supply Voltage		2.375	2.5	2.625	V
$V_{DDO}$	Output Supply Voltage		1.6	1.8	2.0	V
$I_{DD}$	Power Supply Current	No Load & XTALx selected		15		mA
		No Load & CLK0 selected		0		mA
$I_{DDO}$	Output Supply Current	No Load & CLK0 selected		0		mA

TABLE 4F. LVCMOS/LVTTL DC CHARACTERISTICS,  $T_A = -40^\circ C$  TO  $85^\circ C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH}$	Input High Voltage	$V_{DD} = 3.3V \pm 5\%$	2.2		$V_{DD} + 0.3$	V
		$V_{DD} = 2.5V \pm 5\%$	1.6		$V_{DD} + 0.3$	V
$V_{IL}$	Input Low Voltage	$V_{DD} = 3.3V \pm 5\%$	-0.3		1.3	V
		$V_{DD} = 2.5V \pm 5\%$	-0.3		0.9	V
$I_{IH}$	Input High Current	CLK0, CLK_SEL0:1 $V_{DD} = 3.3V$ or $2.5V \pm 5\%$			150	$\mu A$
		OE $V_{DD} = 3.3V$ or $2.5V \pm 5\%$			5	$\mu A$
$I_{IL}$	Input Low Current	CLK0, CLK_SEL0:1 $V_{DD} = 3.3V$ or $2.5V \pm 5\%$	-5			$\mu A$
		OE $V_{DD} = 3.3V$ or $2.5V \pm 5\%$	-150			$\mu A$
$V_{OH}$	Output High Voltage	$V_{DDO} = 3.3V \pm 5\%$ ; NOTE 1	2.6			V
		$V_{DDO} = 2.5V \pm 5\%$ ; NOTE 1	1.8			V
		$V_{DDO} = 1.8V \pm 0.2V$ ; NOTE 1	1.2			V
$V_{OL}$	Output Low Voltage	$V_{DDO} = 3.3V \pm 5\%$ ; NOTE 1			0.6	V
		$V_{DDO} = 2.5V \pm 5\%$ ; NOTE 1			0.5	V
		$V_{DDO} = 1.8V \pm 0.2V$ ; NOTE 1			0.4	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{DDO}/2$ . See Parameter Measurement section, "Load Test Circuit" diagrams.

TABLE 5. CRYSTAL CHARACTERISTICS

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation / cut		Fundamental			
Frequency		10		40	MHz
Equivalent Series Resistance (ESR)				50	$\Omega$
Shunt Capacitance				7	pF
Drive Level				1	mW

TABLE 6A. AC CHARACTERISTICS,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{MAX}$	Output Frequency	w/External XTAL	10		40	MHz
		w/External CLK		200		MHz
$tp_{LH}$	Propagation Delay, Low-to-High; NOTE 1			2		ns
$tsk(o)$	Output Skew; NOTE 2			TBD		ps
$tsk(pp)$	Part-to-Part Skew; NOTE 2, 3			TBD		ps
$f_{jit}(\emptyset)$	RMS Phase Jitter, Random; NOTE 2, 4	25MHz, (100Hz - 1MHz)		0.22		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%		457		ps
odc	Output Duty Cycle			50		%
$t_{EN}$	Output Enable Time; NOTE 5				10	ns
$t_{DIS}$	Output Disable Time; NOTE 5				8	ns

NOTE 1: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.

NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at  $V_{DDO}/2$ .

NOTE 4: Phase jitter is dependent on the input source used.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

TABLE 6B. AC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 2.5V \pm 5\%$ ,  $T_A = -40^\circ\text{C}$  TO  $85^\circ\text{C}$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{MAX}$	Output Frequency	w/External XTAL	10		40	MHz
		w/External CLK		200		MHz
$tp_{LH}$	Propagation Delay, Low-to-High; NOTE 1			2.2		ns
$tsk(o)$	Output Skew; NOTE 2			TBD		ps
$tsk(pp)$	Part-to-Part Skew; NOTE 2, 3			TBD		ps
$f_{jit}(\emptyset)$	RMS Phase Jitter, Random; NOTE 2, 4	25MHz, (100Hz - 1MHz)		0.21		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%		463		ps
odc	Output Duty Cycle			50		%
$t_{EN}$	Output Enable Time; NOTE 5				10	ns
$t_{DIS}$	Output Disable Time; NOTE 5				8	ns

NOTE 1: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.

NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at  $V_{DDO}/2$ .

NOTE 4: Phase jitter is dependent on the input source used.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

TABLE 6C. AC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{MAX}$	Output Frequency	w/External XTAL	10		40	MHz
		w/External CLK		200		MHz
$tp_{LH}$	Propagation Delay, Low-to-High; NOTE 1			2.5		ns
$tsk(o)$	Output Skew; NOTE 2			TBD		ps
$tsk(pp)$	Part-to-Part Skew; NOTE 2, 3			TBD		ps
$f_{jit}(\emptyset)$	RMS Phase Jitter, Random; NOTE 2, 4	25MHz, (100Hz - 1MHz)		0.22		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%		487		ps
odc	Output Duty Cycle			50		%
$t_{EN}$	Output Enable Time; NOTE 5				10	ns
$t_{DIS}$	Output Disable Time; NOTE 5				8	ns

NOTE 1: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.

NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at  $V_{DDO}/2$ .

NOTE 4: Phase jitter is dependent on the input source used.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

TABLE 6D. AC CHARACTERISTICS,  $V_{DD} = V_{DDO} = 2.5V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{MAX}$	Output Frequency	w/External XTAL	10		40	MHz
		w/External CLK		200		MHz
$tp_{LH}$	Propagation Delay, Low-to-High; NOTE 1			2.3		ns
$tsk(o)$	Output Skew; NOTE 2			TBD		ps
$tsk(pp)$	Part-to-Part Skew; NOTE 2, 3			TBD		ps
$f_{jit}(\emptyset)$	RMS Phase Jitter, Random; NOTE 2, 4	25MHz, (100Hz - 1MHz)		0.29		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%		470		ps
odc	Output Duty Cycle			50		%
$t_{EN}$	Output Enable Time; NOTE 5				10	ns
$t_{DIS}$	Output Disable Time; NOTE 5				8	ns

NOTE 1: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.

NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at  $V_{DDO}/2$ .

NOTE 4: Phase jitter is dependent on the input source used.

NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

TABLE 6E. AC CHARACTERISTICS,  $V_{DD} = 2.5V \pm 5\%$ ,  $V_{DDO} = 1.8V \pm 0.2V$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{MAX}$	Output Frequency	w/External XTAL	10		40	MHz
		w/External CLK		200		MHz
$t_{pLH}$	Propagation Delay, Low-to-High; NOTE 1			2.6		ns
$t_{sk(o)}$	Output Skew; NOTE 2			TBD		ps
$t_{sk(pp)}$	Part-to-Part Skew; NOTE 2, 3			TBD		ps
$f_{jit}(\emptyset)$	RMS Phase Jitter, Random; NOTE 2, 4	25MHz, (100Hz - 1MHz)		0.3		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%		518		ps
odc	Output Duty Cycle			50		%
$t_{EN}$	Output Enable Time; NOTE 5				10	ns
$t_{DIS}$	Output Disable Time; NOTE 5				8	ns

NOTE 1: Measured from  $V_{DD}/2$  of the input to  $V_{DDO}/2$  of the output.

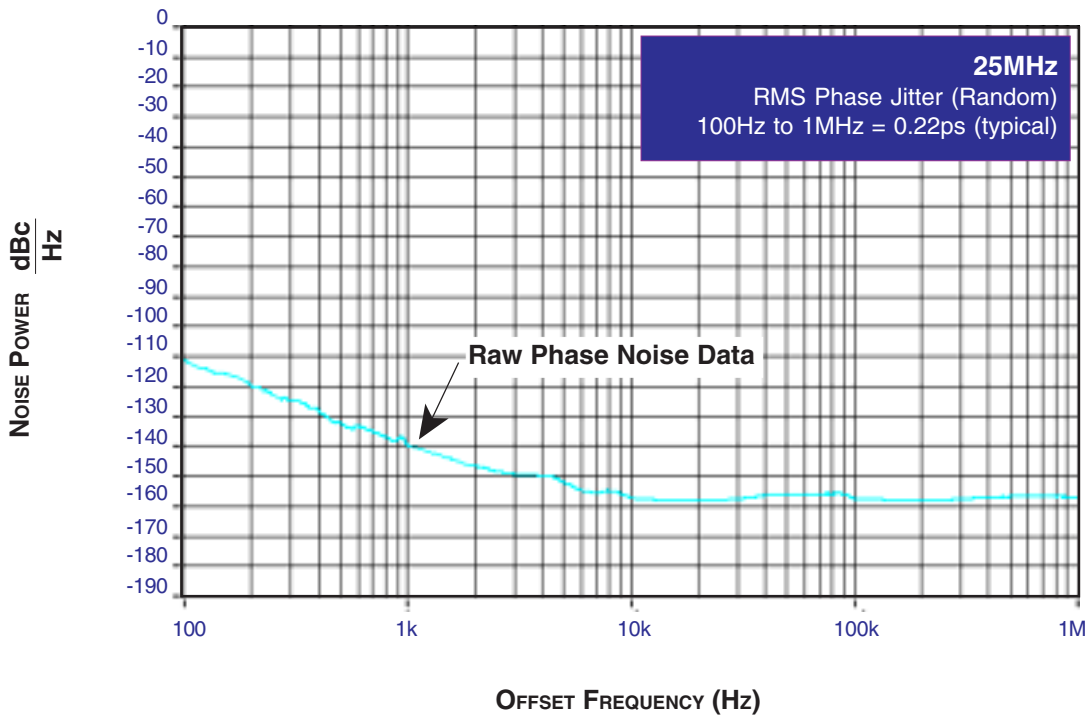
NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of input on each device, the output is measured at  $V_{DDO}/2$ .

NOTE 4: Phase jitter is dependent on the input source used.

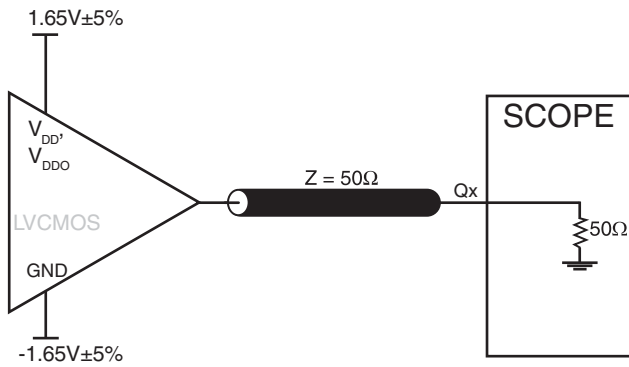
NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

### TYPICAL PHASE NOISE AT 25MHz @ 3.3V

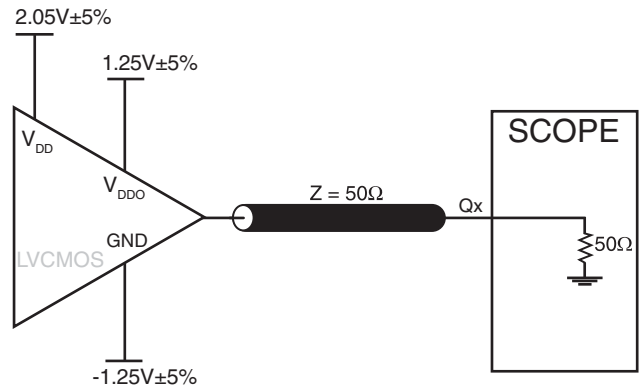




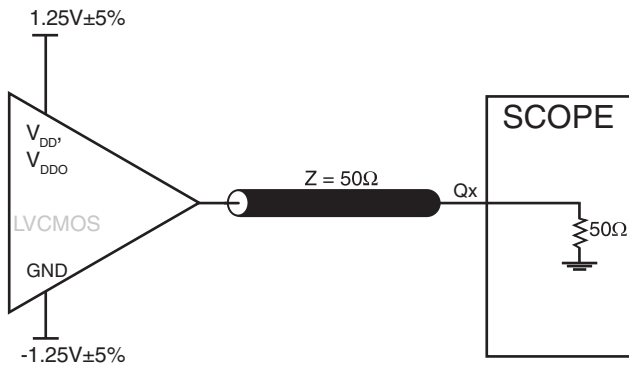
## PARAMETER MEASUREMENT INFORMATION



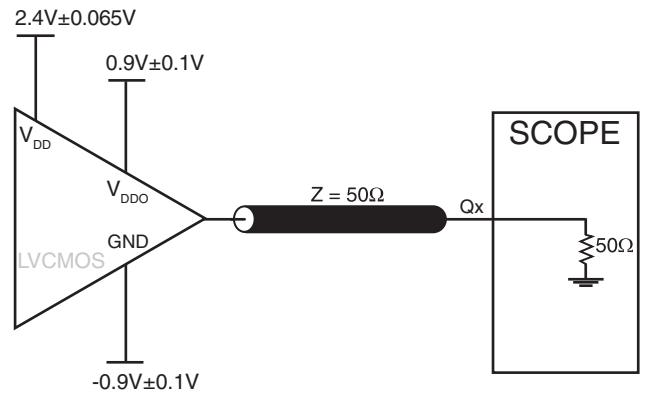
3.3V CORE/3.3V OUTPUT LOAD AC TEST CIRCUIT



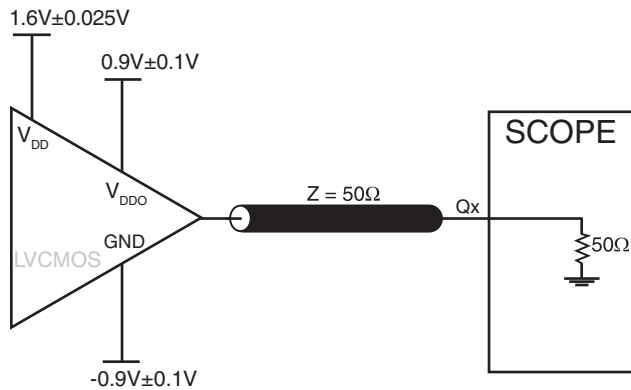
3.3V CORE/2.5V OUTPUT LOAD AC TEST CIRCUIT



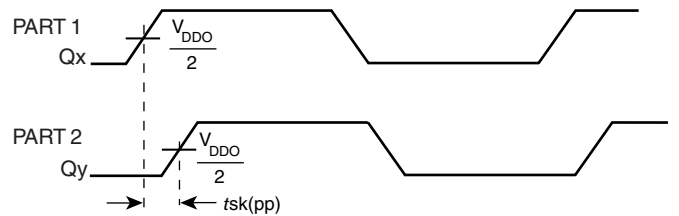
2.5V CORE/2.5V OUTPUT LOAD AC TEST CIRCUIT



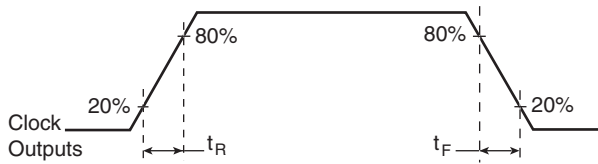
3.3V CORE/1.8V OUTPUT LOAD AC TEST CIRCUIT



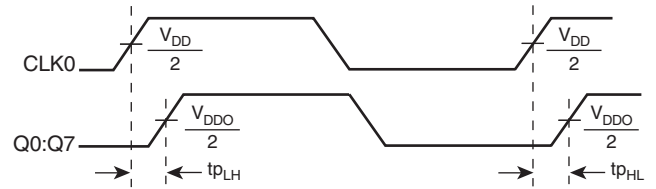
2.5V CORE/1.8V OUTPUT LOAD AC TEST CIRCUIT



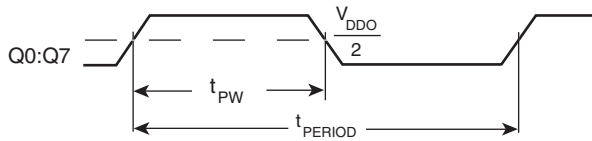
PART-TO-PART SKEW



OUTPUT RISE/FALL TIME



PROPAGATION DELAY



$$\text{odc} = \frac{t_{PW}}{t_{PERIOD}} \times 100\%$$

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

## APPLICATION INFORMATION

### CRYSTAL INPUT INTERFACE

A crystal can be characterized for either series or parallel mode operation. The ICS83908I-02 has a built-in crystal oscillator circuit. This interface can accept either a series or parallel crystal without additional components and generate fre-

quencies with accuracy suitable for most applications. Additional accuracy can be achieved by adding two small capacitors C1 and C2 as shown in *Figure 1*. Typical results using parallel 18pF crystals are shown in Table 5.

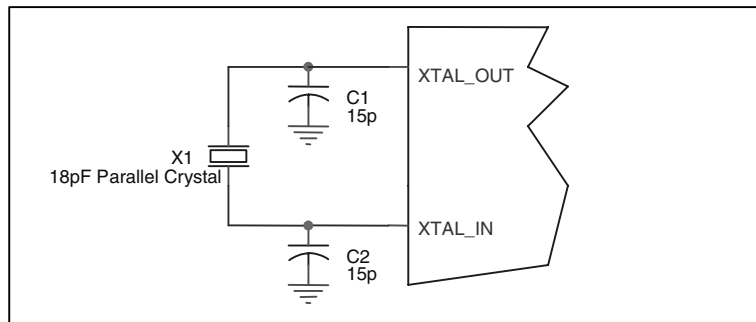


FIGURE 1. Crystal Input Interface

### LVCMOS TO XTAL INTERFACE

The XTAL\_IN input can accept a single-ended LVCMOS signal through an AC coupling capacitor. A general interface diagram is shown in *Figure 2*. The XTAL\_OUT pin can be left floating. The input edge rate can be as slow as 10ns. For LVCMOS inputs, it is recommended that the amplitude be reduced from full swing to half swing in order to prevent signal interference with the power rail and to reduce noise. This configuration requires that the output

impedance of the driver ( $R_o$ ) plus the series resistance ( $R_s$ ) equals the transmission line impedance. In addition, matched termination at the crystal input will attenuate the signal in half. This can be done in one of two ways. First,  $R_1$  and  $R_2$  in parallel should equal the transmission line impedance. For most 50 $\Omega$  applications,  $R_1$  and  $R_2$  can be 100 $\Omega$ . This can also be accomplished by removing  $R_1$  and making  $R_2$  50 $\Omega$ .

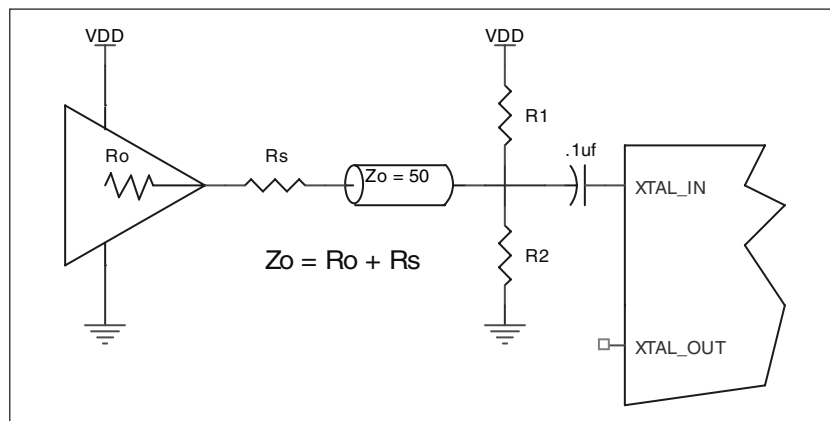


FIGURE 2. GENERAL DIAGRAM FOR LVCMOS DRIVER TO XTAL INPUT INTERFACE

## RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

### INPUTS:

#### CLK INPUT

For applications not requiring the use of the test clock, it can be left floating. Though not required, but for additional protection, a 1k $\Omega$  resistor can be tied from the CLK input to ground.

#### CRYSTAL INPUTS

For applications not requiring the use of the crystal oscillator input, both XTAL\_IN and XTAL\_OUT can be left floating. Though not required, but for additional protection, a 1k $\Omega$  resistor can be tied from XTAL\_IN to ground.

#### LVCMOS CONTROL PINS

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A 1k $\Omega$  resistor can be used.

### OUTPUTS:

#### LVCMOS OUTPUTS

All unused LVCMOS output can be left floating. There should be no trace attached.

## RELIABILITY INFORMATION

TABLE 7.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 24 LEAD TSSOP

$\theta_{JA}$ by Velocity (Meters per Second)			
	0	1	2.5
Multi-Layer PCB, JEDEC Standard Test Boards	84.6°C/W	80.3°C/W	78.1°C/W

### TRANSISTOR COUNT

The transistor count for ICS83908I-02 is: 277

## PACKAGE OUTLINE - G SUFFIX FOR 24 LEAD TSSOP

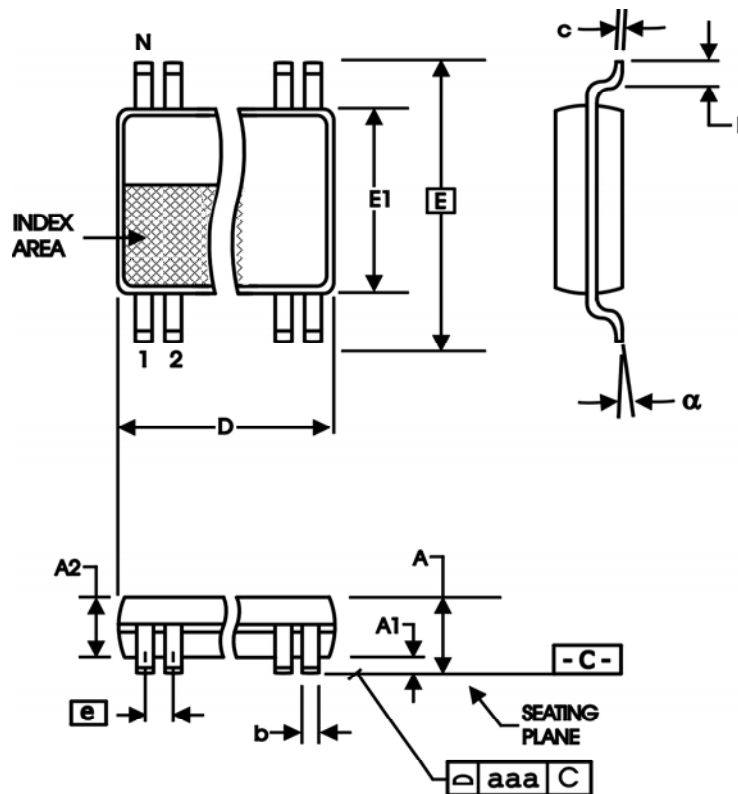


TABLE 8. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	Minimum	Maximum
N	24	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	7.70	7.90
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
$\alpha$	0°	8°
aaa	--	0.10

REFERENCE DOCUMENT: JEDEC PUBLICATION 95, MO-153

TABLE 9. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS83908AGI-02	TBD	24 Lead TSSOP	tube	-40°C to 85°C
ICS83908AGI-02T	TBD	24 Lead TSSOP	2500 tape & reel	-40°C to 85°C
ICS83908AGI-02LF	ICS83908AI02L	24 Lead "Lead-Free" TSSOP	tube	-40°C to 85°C
ICS83908AGI-02LFT	ICS83908AI02L	24 Lead "Lead-Free" TSSOP	2500 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

While the information presented herein has been checked for both accuracy and reliability, Integrated Device Technology, Incorporated (IDT) assumes no responsibility for either its use or for infringement of any patents or other rights of third parties, which would result from its use. No other circuits, patents, or licenses are implied. This product is intended for use in normal commercial and industrial applications. Any other applications such as those requiring high reliability or other extraordinary environmental requirements are not recommended without additional processing by IDT. IDT reserves the right to change any circuitry or specifications without notice. IDT does not authorize or warrant any IDT product for use in life support devices or critical medical instruments.

Innovate with IDT and accelerate your future networks. Contact:

[www.IDT.com](http://www.IDT.com)

**For Sales**

800-345-7015  
408-284-8200  
Fax: 408-284-2775

**For Tech Support**

netcom@idt.com  
480-763-2056

---

**Corporate Headquarters**

Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road  
San Jose, CA 95138  
United States  
800 345 7015  
+408 284 8200 (outside U.S.)

**Asia Pacific and Japan**

Integrated Device Technology  
Singapore (1997) Pte. Ltd.  
Reg. No. 199707558G  
435 Orchard Road  
#20-03 Wisma Atria  
Singapore 238877  
+65 6 887 5505

**Europe**

IDT Europe, Limited  
321 Kingston Road  
Leatherhead, Surrey  
KT22 7TU  
England  
+44 (0) 1372 363 339  
Fax: +44 (0) 1372 378851



[www.IDT.com](http://www.IDT.com)